



RF360
Europe GmbH

SAW components

SAW duplexer

Small cell & femtocell
LTE band 2

Series/type:	B8047
Ordering code:	B39202B8047P810
Date:	October 05, 2017
Version:	2.0

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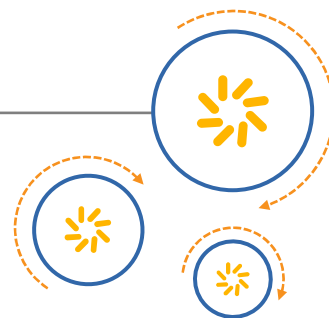
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A Qualcomm – TDK Joint Venture

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SAW components	B8047
SAW duplexer	1880 / 1960 MHz

Data sheet

Table of contents

1	Application	4
2	Features	4
3	Package	5
4	Pin configuration	5
5	Matching circuit	6
6	Characteristics	7
7	Maximum ratings	13
8	Transmission coefficients	14
9	Reflection coefficients	17
10	EVMS	18
11	Packing material	20
12	Marking	24
13	Soldering profile	25
14	Annotations	26
15	Cautions and warnings	27
	Important notes	28

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

1 Application

- Low-loss SAW duplexer for LTE small cell & femtocell systems (Band 2)
- Usable pass band 60 MHz
- RX = uplink = 1850 – 1910 MHz
- TX = downlink = 1930 – 1990 MHz

2 Features

- Industrial grade qualified family
- Package size $2.5 \pm 0.1 \text{ mm} \times 2.0 \pm 0.1 \text{ mm}$
- Package height 0.5 mm (max.)
- Approximate weight 0.01 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

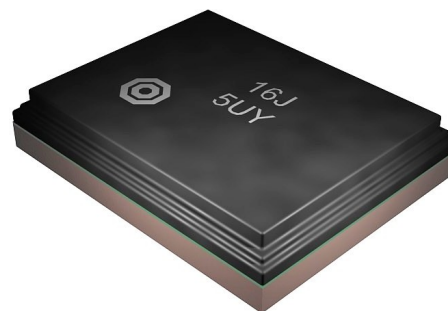


Figure 1: Picture of component with example of product marking.

SAW components

B8047

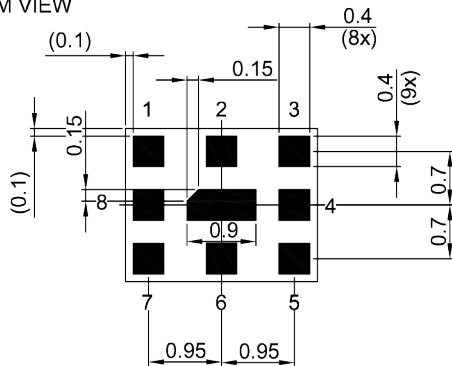
SAW duplexer

1880 / 1960 MHz

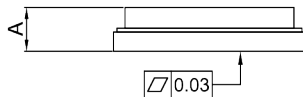
Data sheet

3 Package

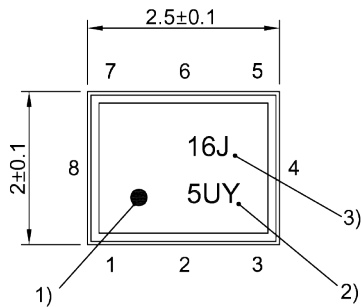
BOTTOM VIEW

Pad and pitch tolerance ± 0.05

SIDE VIEW



TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

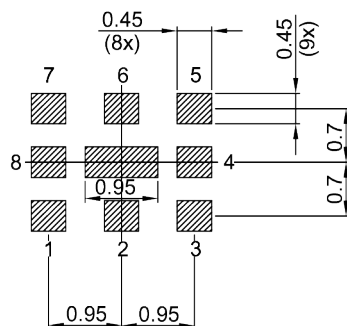
Land pattern
THRU VIEWLanding pad tolerance -0.02

Figure 2: Drawing of package with package height $A = 0.5$ mm (max.). See Sec. Package information (p. 27).

4 Pin configuration

- 1 TX
- 3 RX
- 6 ANT
- 2, 4, 5, 7, 8, 9 Ground

Data sheet

5 Matching circuit

$$\blacksquare L_{p1} = 8.2 \text{ nH}$$

$$\blacksquare L_{p6} = 3.6 \text{ nH}$$

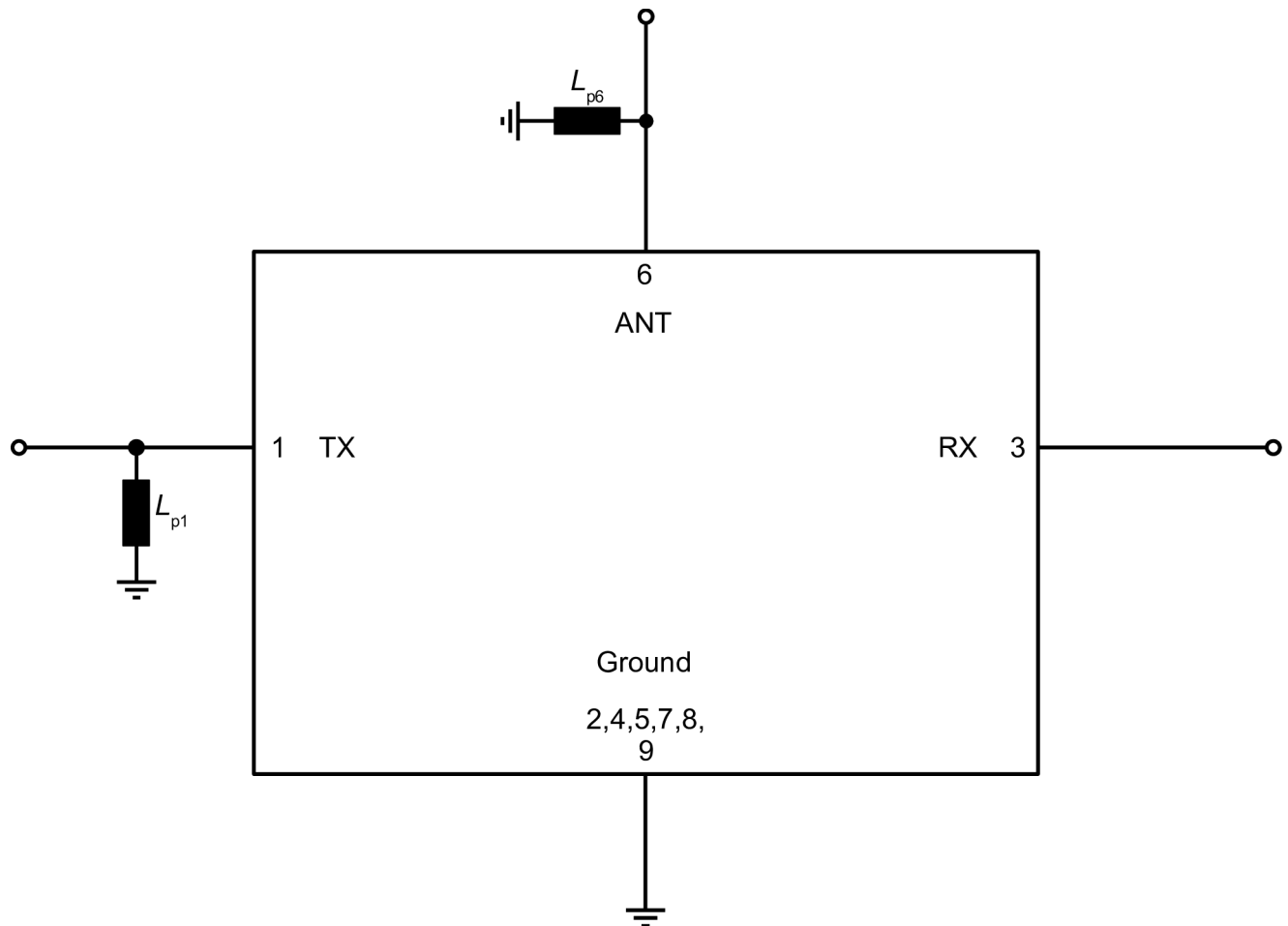


Figure 3: Schematic of matching circuit.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

6 Characteristics

6.1 TX – ANT

Temperature range for specification

 $T_{SPEC} = -10\text{ °C} \dots +85\text{ °C}$

TX terminating impedance

 $Z_{TX} = 50\ \Omega$ with par. 8.2 nH¹⁾

ANT terminating impedance

 $Z_{ANT} = 50\ \Omega$ with par. 3.6 nH¹⁾

RX terminating impedance

 $Z_{RX} = 50\ \Omega$

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency		f_C		—	1960	—	MHz
Average insertion attenuation		$\alpha_{INT,avg}$ ²⁾					
	1930... 1935	MHz		—	1.7	2.7	dB
	1935... 1985	MHz		—	1.4	2.7	dB
	1985... 1990	MHz		—	1.4	2.7	dB
Maximum insertion attenuation		α_{max}					
	1930.24... 1989.76	MHz		—	2.0	3.0	dB
Amplitude ripple (p-p)		$\Delta\alpha$					
	1930.24... 1989.76	MHz		—	0.9	2.0	dB
Maximum VSWR		VSWR _{max}					
@ TX port	1930.24... 1989.76	MHz		—	1.5	2.0	
@ ANT port	1930.24... 1989.76	MHz		—	1.4	2.0	
Maximum error vector magnitude		EVM _{max} ³⁾					
	1932.4... 1987.6	MHz		—	1.0	—	%
Minimum attenuation		α_{min}					
	50... 1574	MHz		35	37	—	dB
	1574... 1606	MHz		35	38	—	dB
	1606... 1710	MHz		35	39	—	dB
	1710... 1780	MHz		35	42	—	dB
	1780... 1850.24	MHz		35	44	—	dB
	1850.24... 1909.76	MHz		45	48	—	dB
	2110... 2200	MHz		35	45	—	dB
	2200... 2300	MHz		35	45	—	dB
	2400... 2500	MHz		5	16	—	dB
	2500... 2535	MHz		5	50	—	dB
	2535... 5150	MHz		35	42	—	dB
	5150... 5850	MHz		30	42	—	dB

¹⁾ See Sec. Matching circuit (p. 6).²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω with par. 8.2 nH ¹⁾
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Average insertion attenuation						
		$\alpha_{INT,avg}^{2)}$				
	1930... 1935	MHz	—	1.7	3.0	dB
	1935... 1985	MHz	—	1.4	3.0	dB
	1985... 1990	MHz	—	1.4	3.0	dB
Maximum insertion attenuation						
		α_{max}				
	1930.24... 1989.76	MHz	—	2.0	3.5	dB
Amplitude ripple (p-p)						
		$\Delta\alpha$				
	1930.24... 1989.76	MHz	—	0.9	2.5	dB
Maximum VSWR						
		$VSWR_{max}$				
@ TX port	1930.24... 1989.76	MHz	—	1.5	2.0	
@ ANT port	1930.24... 1989.76	MHz	—	1.4	2.0	
Maximum error vector magnitude						
		$EVM_{max}^{3)}$				
	1932.4... 1987.6	MHz	—	1.0	—	%
Minimum attenuation						
		α_{min}				
	50... 1574	MHz	35	37	—	dB
	1574... 1606	MHz	35	38	—	dB
	1606... 1710	MHz	35	39	—	dB
	1710... 1780	MHz	35	42	—	dB
	1780... 1850.24	MHz	35	44	—	dB
	1850.24... 1909	MHz	45	48	—	dB
	1909... 1909.76	MHz	35	59	—	dB
	2110... 2200	MHz	35	45	—	dB
	2200... 2300	MHz	35	45	—	dB
	2400... 2500	MHz	5	16	—	dB
	2500... 2535	MHz	5	50	—	dB
	2535... 5150	MHz	35	42	—	dB
	5150... 5850	MHz	30	42	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

6.2 ANT – RX

Temperature range for specification

$$T_{\text{SPEC}} = -10\text{ }^{\circ}\text{C} \dots +85\text{ }^{\circ}\text{C}$$

TX terminating impedance

$$Z_{\text{TX}} = 50\text{ }\Omega \text{ with par. } 8.2\text{ nH}^{1)}$$

ANT terminating impedance

$$Z_{\text{ANT}} = 50\text{ }\Omega \text{ with par. } 3.6\text{ nH}^{1)}$$

RX terminating impedance

$$Z_{\text{RX}} = 50\text{ }\Omega$$

Characteristics ANT – RX

				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency				f_{C}	1880	—	MHz
Average insertion attenuation				$\alpha_{\text{INT,avg}}^{2)}$			
	1850... 1855	MHz		—	1.6	2.7	dB
	1855... 1905	MHz		—	1.5	2.7	dB
	1905... 1910	MHz		—	1.6	2.7	dB
Maximum insertion attenuation				α_{max}			
	1850.24... 1909.76	MHz		—	2.0	3.0	dB
Amplitude ripple (p-p)				$\Delta\alpha$			
	1850.24... 1909.76	MHz		—	1.0	2.0	dB
Maximum VSWR				VSWR_{max}			
@ ANT port	1850.24... 1909.76	MHz		—	1.6	2.0 ³⁾	
@ RX port	1850.24... 1909.76	MHz		—	1.6	2.0 ⁴⁾	
Maximum error vector magnitude				$\text{EVM}_{\text{max}}^{5)}$			
	1852.4... 1907.6	MHz		—	1.3	—	%
Minimum attenuation				α_{min}			
	50... 1574	MHz		35	42	—	dB
	1574... 1606	MHz		35	48	—	dB
	1606... 1710	MHz		35	50	—	dB
	1710... 1780	MHz		30	40	—	dB
	1780... 1830	MHz		10	37	—	dB
	1930.24... 1989.76	MHz		45	52	—	dB
	1989.76... 2110	MHz		35	48	—	dB
	2110... 2200	MHz		35	54	—	dB
	2200... 2250	MHz		35	55	—	dB
	2250... 2300	MHz		5	45	—	dB
	2400... 2500	MHz		5	30	—	dB
	2500... 5150	MHz		20	30	—	dB
	5150... 5850	MHz		15	26	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

³⁾ Valid for temperature $T = -10\text{ }^{\circ}\text{C} \dots +45\text{ }^{\circ}\text{C}$, VSWR 2.2 for $-10\text{ }^{\circ}\text{C} \dots +85\text{ }^{\circ}\text{C}$.

⁴⁾ Valid for temperature $T = -10\text{ }^{\circ}\text{C} \dots +45\text{ }^{\circ}\text{C}$, VSWR 2.1 for $-10\text{ }^{\circ}\text{C} \dots +85\text{ }^{\circ}\text{C}$.

⁵⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω with par. 8.2 nH ¹⁾
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Average insertion attenuation						
		$\alpha_{INT,avg}$ ²⁾				
	1850... 1855	MHz	—	1.6	3.0	dB
	1855... 1905	MHz	—	1.5	3.0	dB
	1905... 1910	MHz	—	1.6	3.0	dB
Maximum insertion attenuation						
	1850.24... 1909.76	MHz	—	2.0	3.5	dB
Amplitude ripple (p-p)						
	1850.24... 1909.76	MHz	—	1.0	2.5	dB
Maximum VSWR						
		VSWR _{max}				
@ ANT port	1850.24... 1909.76	MHz	—	1.6	2.3	
@ RX port	1850.24... 1909.76	MHz	—	1.6	2.3	
Maximum error vector magnitude						
	1852.4... 1907.6	MHz	—	1.3	—	%
Minimum attenuation						
		α_{min}				
	50... 1574	MHz	35	42	—	dB
	1574... 1606	MHz	35	48	—	dB
	1606... 1710	MHz	35	50	—	dB
	1710... 1780	MHz	30	40	—	dB
	1780... 1830	MHz	10	37	—	dB
	1930.24... 1931.5	MHz	30	61	—	dB
	1931.5... 1989.76	MHz	45	52	—	dB
	1989.76... 2110	MHz	35	48	—	dB
	2110... 2200	MHz	35	54	—	dB
	2200... 2250	MHz	35	55	—	dB
	2250... 2300	MHz	5	45	—	dB
	2400... 2500	MHz	5	30	—	dB
	2500... 5150	MHz	20	30	—	dB
	5150... 5850	MHz	15	26	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

³⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

SAW components	B8047
SAW duplexer	1880 / 1960 MHz

Data sheet

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= -10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω with par. 8.2 nH ¹⁾
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Average isolation	1850... 1910 MHz	MHz	$\alpha_{INT,avg}$ ²⁾	47	50	—	dB
				48	56	—	dB
Minimum isolation	1850.24... 1909.76 MHz	MHz	α_{min}	47	50	—	dB
				48	55	—	dB

¹⁾ See Sec. Matching circuit (p. 6).
²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

SAW componentsB8047

SAW duplexer1880 / 1960 MHz

Data sheet

Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω with par. 8.2 nH ¹⁾
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Average isolation	1850... 1910 MHz	$\alpha_{INT,avg}$ ²⁾	47	50	—	dB
			45	56	—	
Minimum isolation	1930... 1990 MHz	α_{min}	47	50	—	dB
	1850.24... 1909 MHz		37	58	—	
	1909... 1909.76 MHz		35	63	—	
	1930.24... 1931.5 MHz		48	55	—	
	1931.5... 1989.76 MHz					

¹⁾ See Sec. Matching circuit (p. 6).
²⁾ Integrated attenuation α_{INT} : Averaged power $|S_{ij}|^2$ over the center 4.5 MHz of LTE 5 MHz (25 RB) channels.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +95\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +95\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
ESD voltage		
	$V_{ESD}^{3)} = 350\text{ V}$	Machine model.
	$V_{ESD}^{4)} = 350\text{ V}$	Human body model.
Input power	P_{IN}	
@ TX port: 1930.24 ... 1989.76 MHz	28 dBm ⁵⁾	5 MHz LTE downlink signal for 100000 h @ 55 °C. P_{IN} average – 39 dBm peak. Source and load impedance 50Ω.
@ TX port: other frequency ranges	10 dBm	Source and load impedance 50Ω.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁵⁾ Expected lifetime according to power durability simulations and wear out models.

Data sheet

8 Transmission coefficients

8.1 TX – ANT

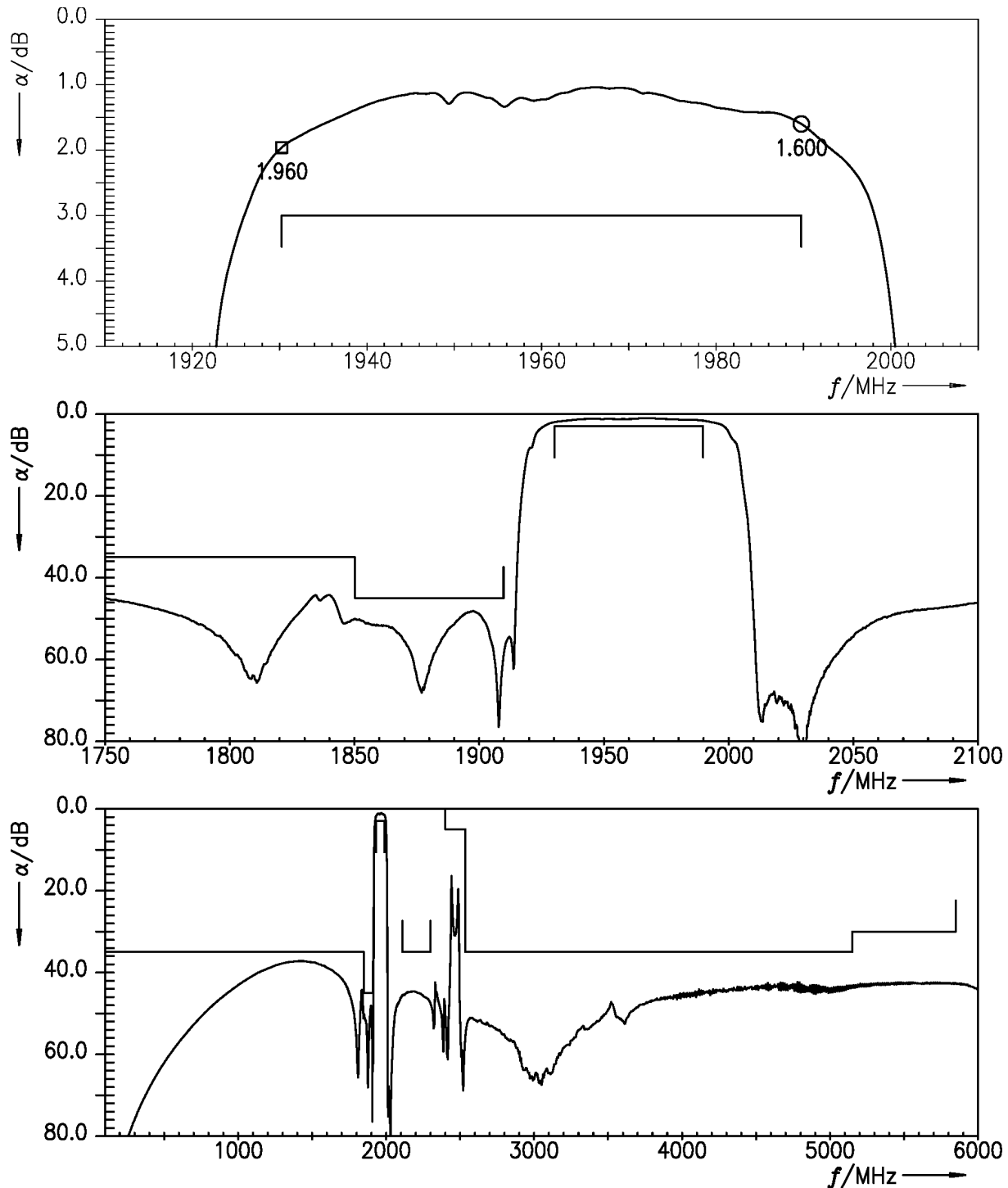


Figure 4: Attenuation TX – ANT.

Data sheet

8.2 ANT – RX

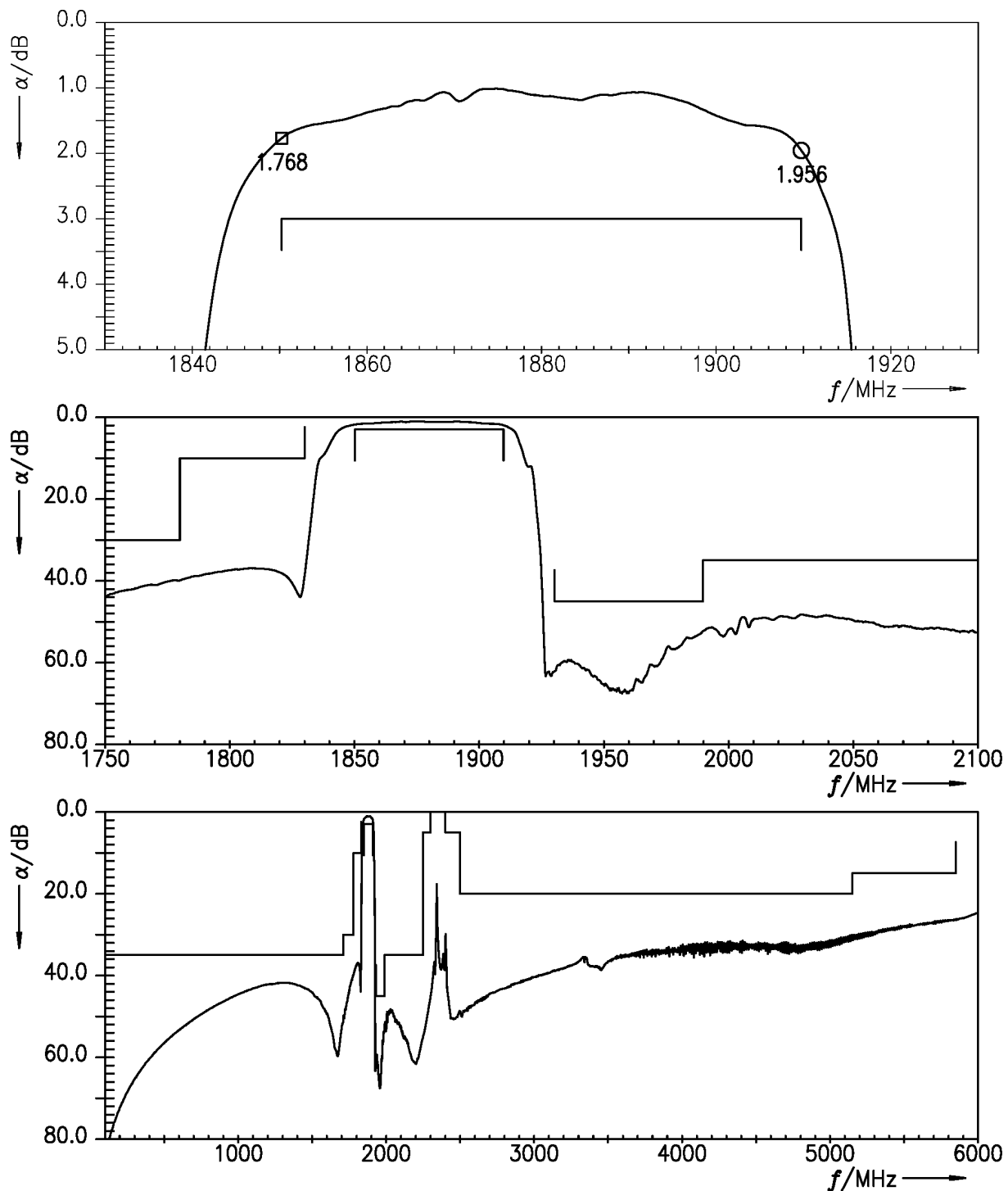


Figure 5: Attenuation ANT – RX.

Data sheet

8.3 TX – RX

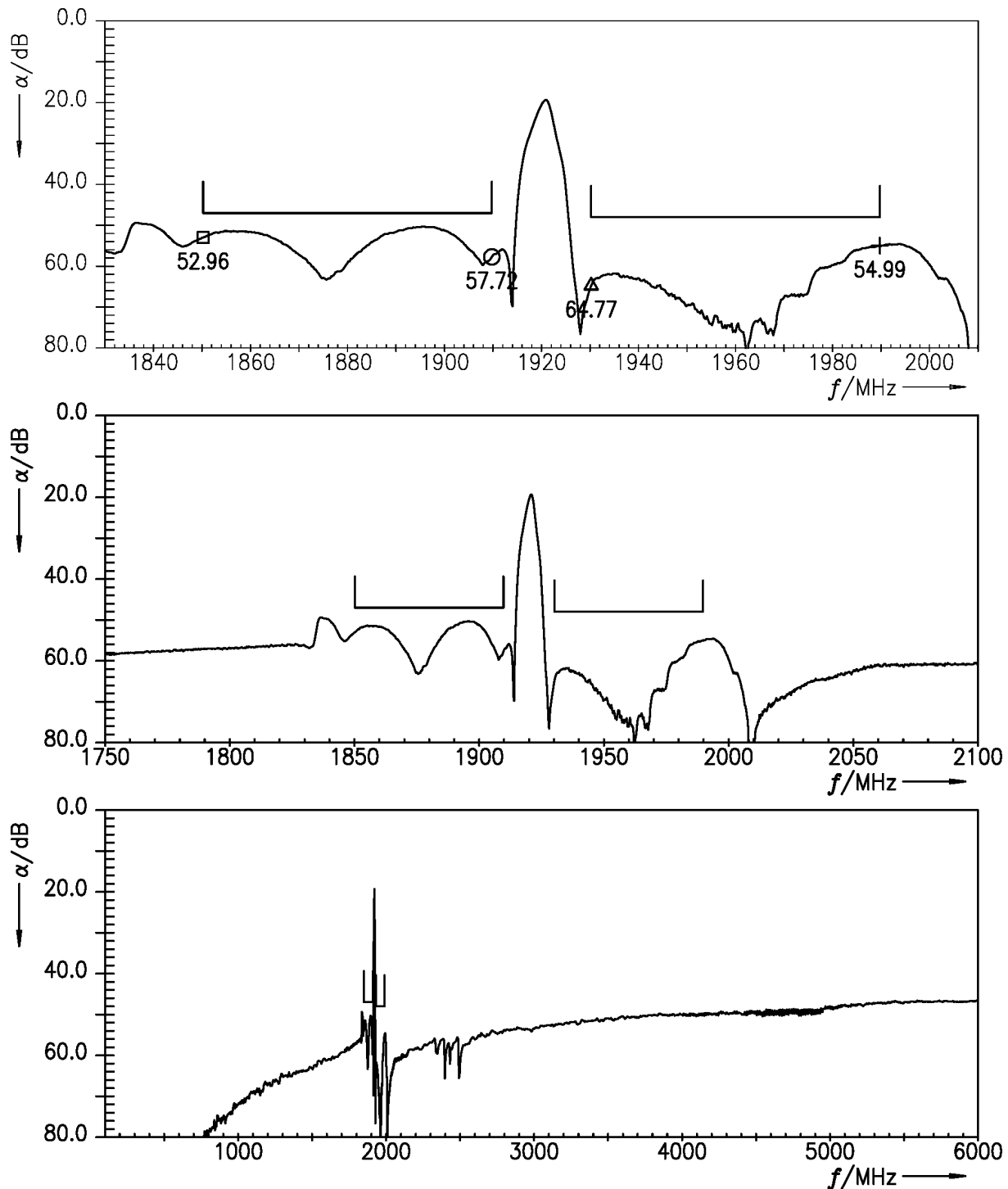


Figure 6: Isolation TX – RX.

Data sheet

9 Reflection coefficients

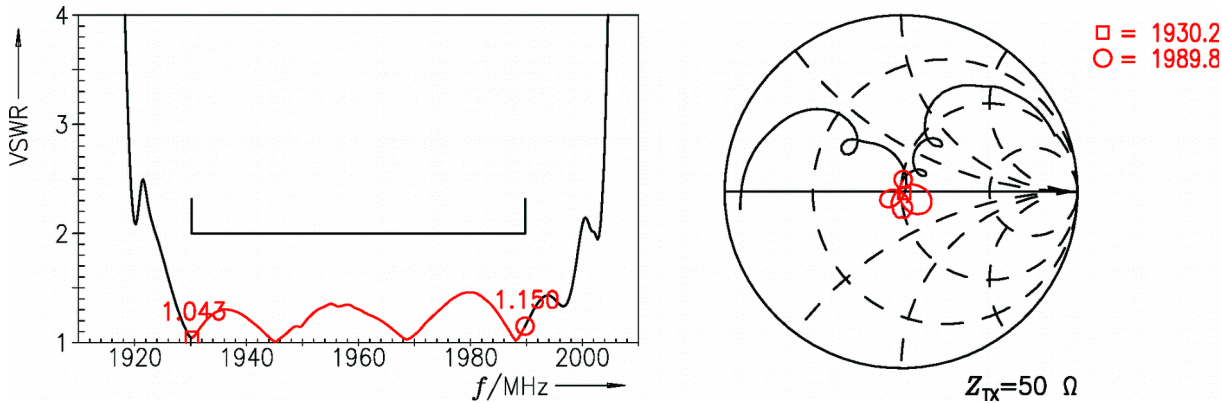


Figure 7: Reflection coefficient at TX port.

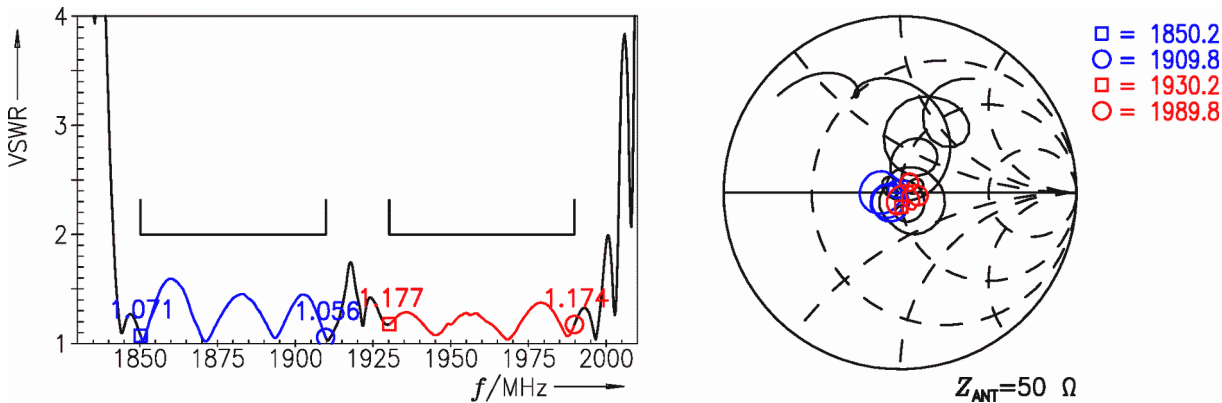


Figure 8: Reflection coefficient at ANT port.

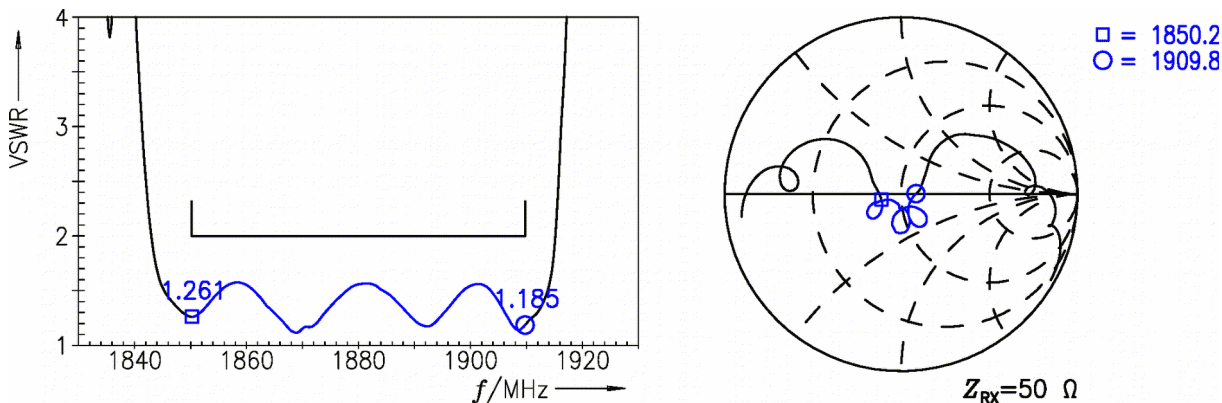
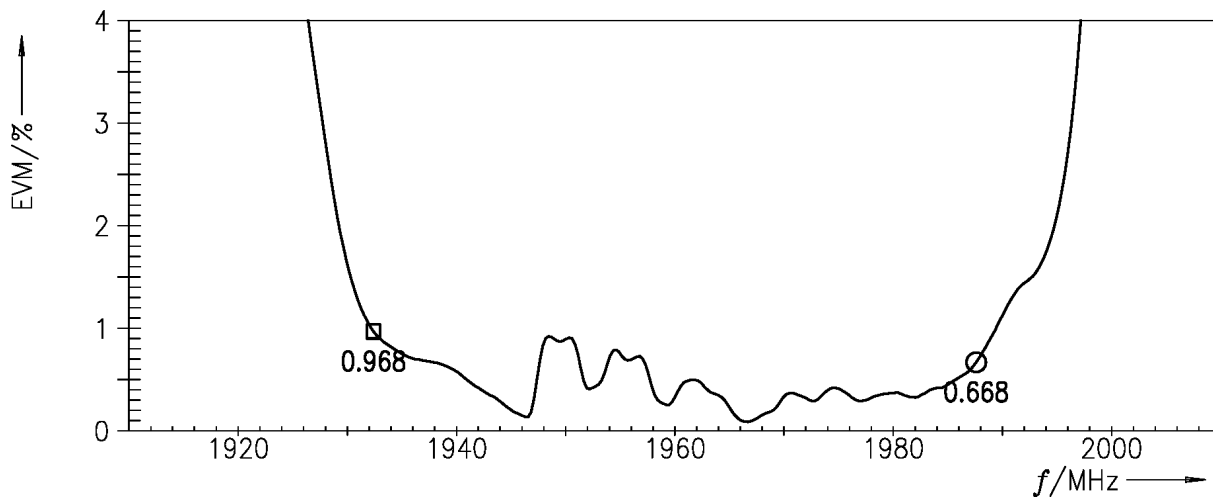


Figure 9: Reflection coefficient at RX port.

Data sheet

10 EVMs**10.1 TX – ANT****Figure 10:** Error vector magnitude TX – ANT.

SAW components	B8047
SAW duplexer	1880 / 1960 MHz

Data sheet

10.2 ANT – RX

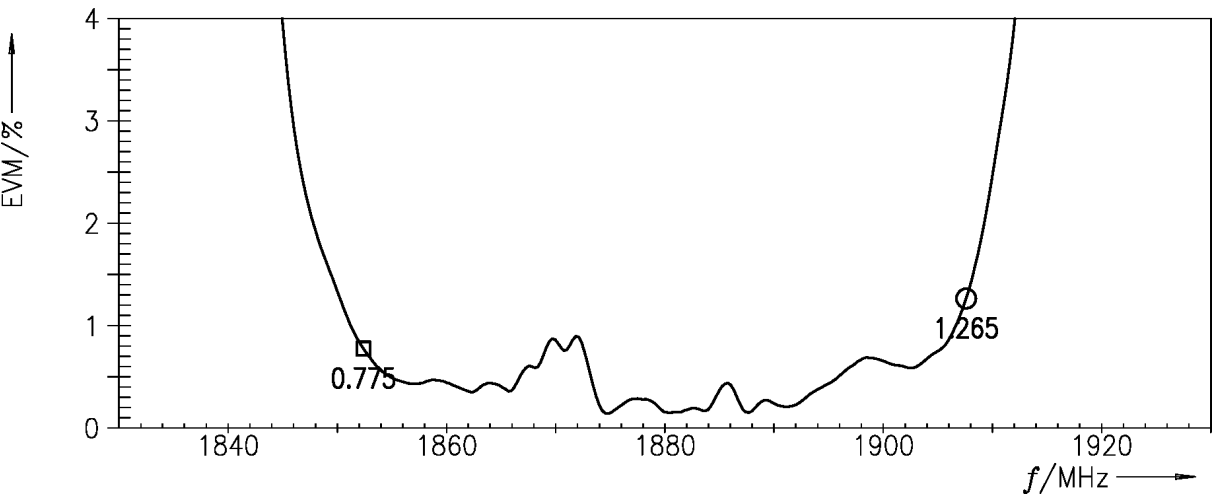


Figure 11: Error vector magnitude ANT – RX.

Data sheet

11 Packing material

11.1 Tape

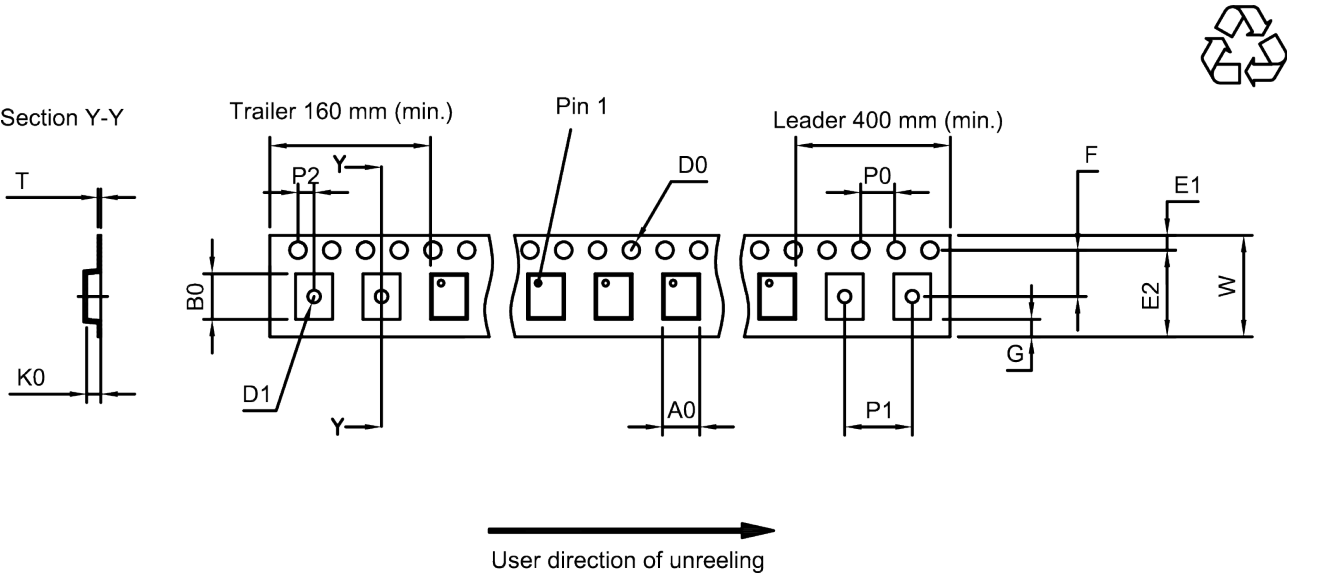


Figure 12: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	2.25±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	2.75±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	1.0 mm (min.)	K ₀	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

SAW components	B8047
SAW duplexer	1880 / 1960 MHz

Data sheet

11.2 Reel with diameter of 180 mm

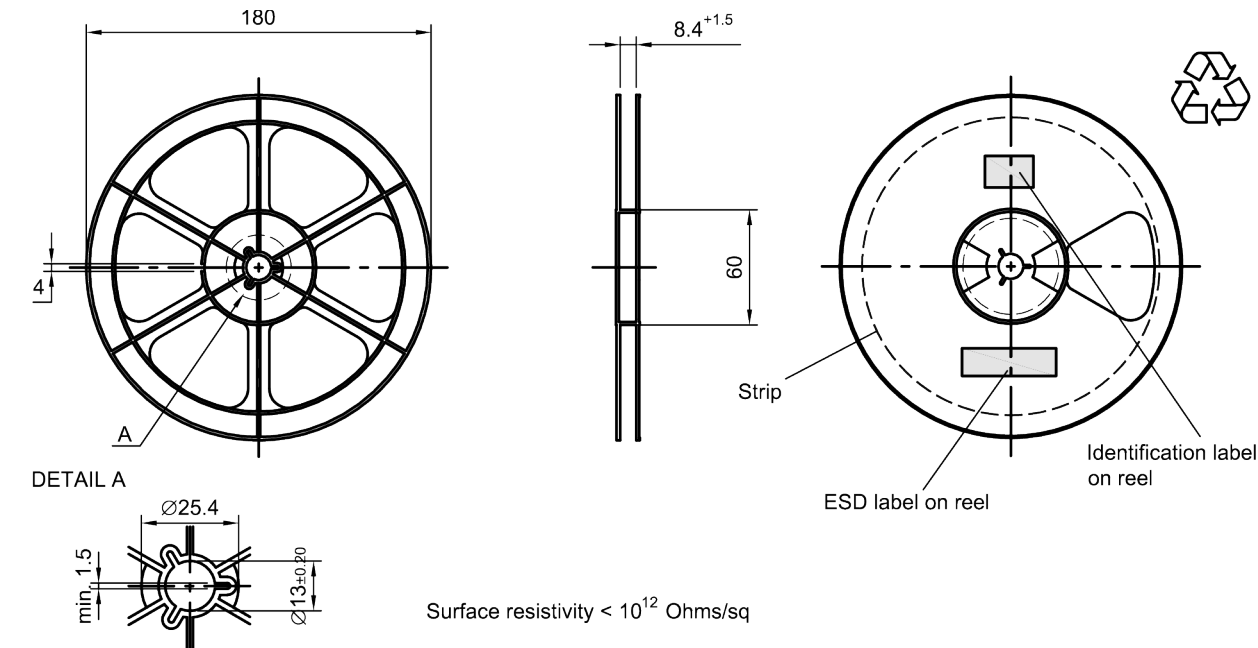


Figure 13: Drawing of reel (first-angle projection) with diameter of 180 mm.

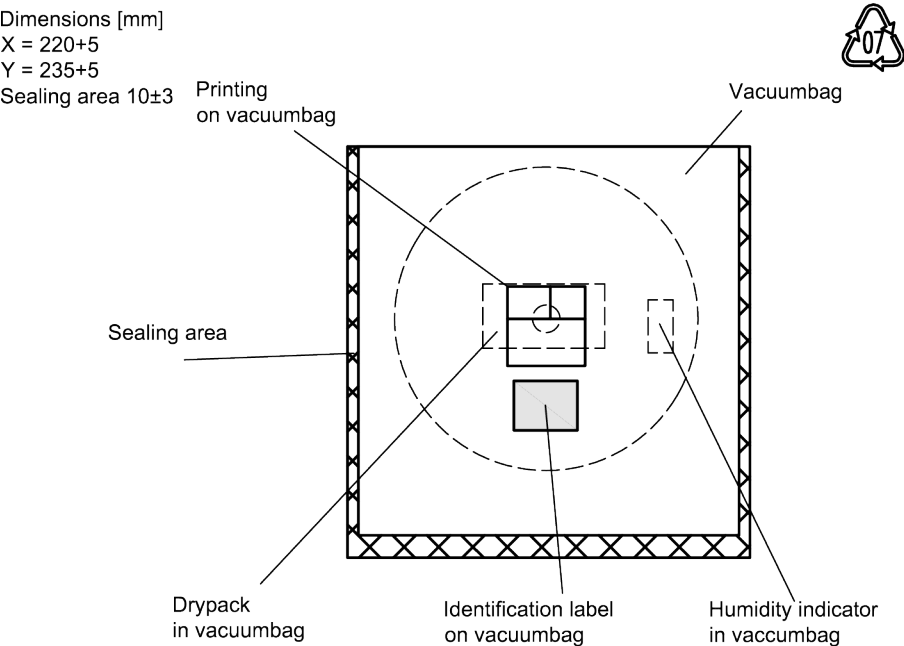


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Data sheet

Dimensions [mm]

L = 188

B = 188

H = 30

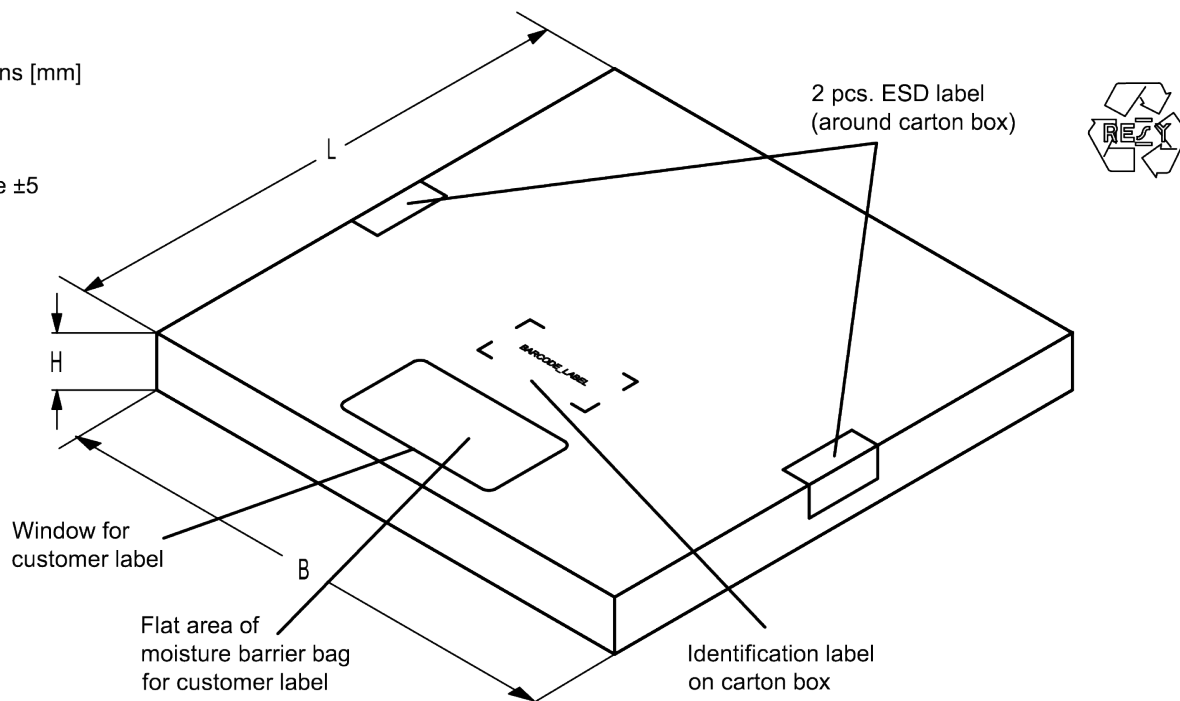
Tolerance ± 5 

Figure 15: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

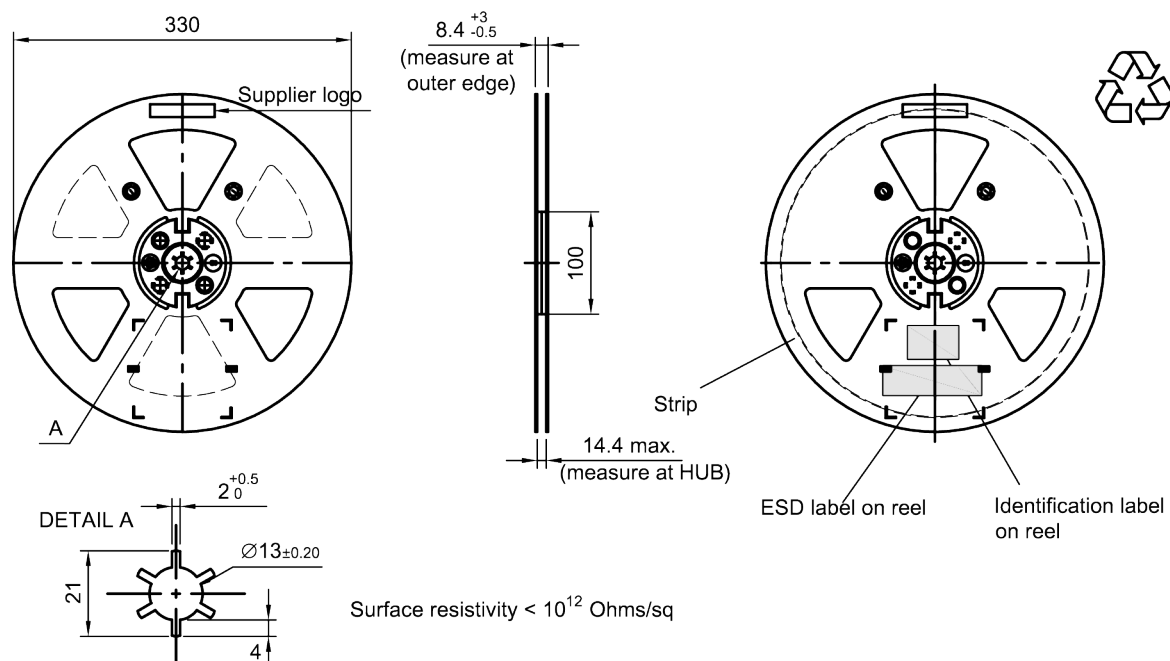


Figure 16: Drawing of reel (first-angle projection) with diameter of 330 mm.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

Dimensions [mm]

X = 400±5

Y = 418±5

Sealing area 10±3

Printing
on vacuumbag

Sealing area

Drypack
in vacuumbagIdentification label
on vacuumbag

Vacuumbag

Humidity indicator
in vacuumbag

Figure 17: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

Dimensions [mm]

L = 335

B = 338

H = 36 (for 8 mm tape width)

40 (for 12 mm tape width)

Tolerance ±5

2 pcs. ESD label
(around carton box)Window for
customer labelFlat area of
moisture barrier bag
for customer labelIdentification label
on carton boxIn case of modules with
additional printing
for badge number
on the upper right side
on the top of the carton box.

Figure 18: Drawing of folding box for reel with diameter of 330 mm.

SAW components

B8047

SAW duplexer

1880 / 1960 MHz

Data sheet

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding	type number marking on device	in decimal code.
16J	=>	1234
$1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$	=	1234

The BASE32 code for product type B8047 is 7VF.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device		in decimal code.
5UY	=>	12345
$5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$	=	12345

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

SAW components	B8047
SAW duplexer	1880 / 1960 MHz

Data sheet

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T _{peak}	250 °C +0/-5 °C
wetting temperature T _{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

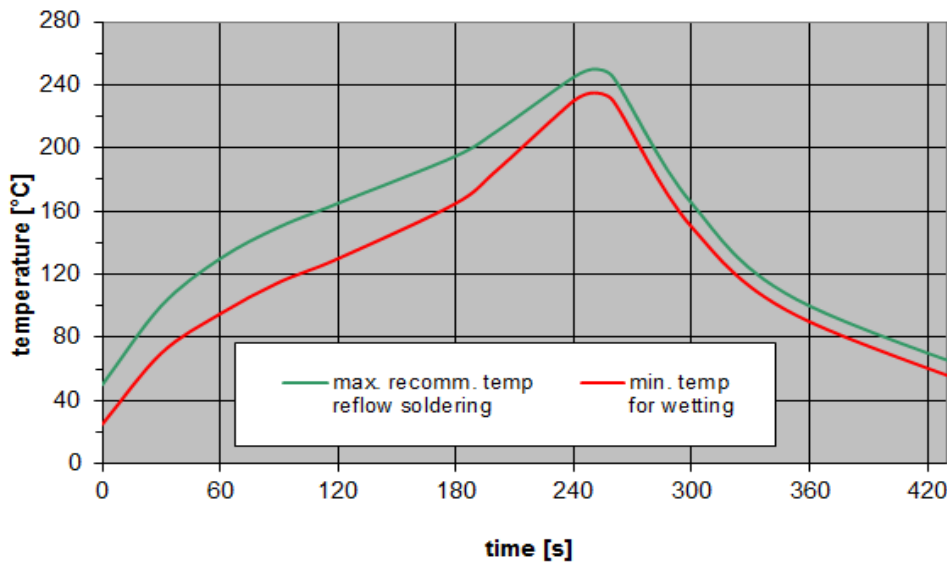


Figure 19: Recommended reflow profile for convection and infrared soldering – lead-free solder.

SAW components**B8047****SAW duplexer****1880 / 1960 MHz**

Data sheet

14 Annotations**14.1 Matching coils**

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.4 Ordering codes and packing units

Ordering code	Packing unit
B39202B8047P810	5000 pcs

Table 4: Ordering codes and packing units.

Data sheet

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.